

**Bump Site Transfer and Qualification of Select 6L and 8L SOT23 Flip Chip on Lead Packages**

**Automotive Qualification Results Summary for  
SOT at CARSEM**

TEST	SPECIFICATION	SAMPLE SIZE	RESULT
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	PASS
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	PASS
Temperature, Humidity and Bias Test (THB)*	JEDEC <i>JESD22-A101</i>	3 x 77	PASS
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	1 x 77	PASS
Unbiased Highly Accelerated Stress Test (UHAST)*	JEDEC <i>JESD22-A118</i>	3 x 77	PASS
Electrostatic Discharge <i>Field Induced Charge Device Model</i>	ANSI/ESDA/JEDEC <i>JS-002-2014</i>	3/voltage	PASS +/1250V

\* These samples will be subjected to preconditioning (per J-STD-020 Level 1) prior to the start of the stress test. Level 1 preconditioning consists of the following: 1. Bake – 24 hours at 125°C; 2. Soak – unbiased soak for 168 hours at 85°C, 85%RH; 3. Reflow – three passes through a reflow oven with a peak temperature of 260°C.